

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Sriram Srinivasan</td> <td>01/02/2013</td> </tr> <tr> <td>Ram S. Viswanath</td> <td>01/03/2013</td> </tr> <tr> <td>Paul R. Start</td> <td>01/02/2013</td> </tr> <tr> <td>Rajen S. Sidhu</td> <td>01/03/2013</td> </tr> <tr> <td>Rajasekaran Swaminathan</td> <td>01/03/2013</td> </tr> </tbody> </table>		Name	Execution Date	Sriram Srinivasan	01/02/2013	Ram S. Viswanath	01/03/2013	Paul R. Start	01/02/2013	Rajen S. Sidhu	01/03/2013	Rajasekaran Swaminathan	01/03/2013
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<table border="1"> <tr> <td>Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Blvd.</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95054</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Blvd.	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95054		
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CORRESPONDENCE DATA													
<p>Fax Number: 6123328352 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 480-715-5488 Email: PAggarwal1@cpaglobal.com Correspondent Name: Intel Corporation Address Line 1: c/o CPA Global Address Line 2: PO Box 52050 Address Line 4: Minneapolis, MINNESOTA 55402</p>													
ATTORNEY DOCKET NUMBER:	P46433												
NAME OF SUBMITTER:	Lee Wolfe												

CH \$40.00 13721329

Signature:	/Lee Wolfe/
Date:	08/14/2013
Total Attachments: 2 source=P46433_Executed_Assignment for filing#page1.tif source=P46433_Executed_Assignment for filing#page2.tif	

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**SRIRAM SRINIVASAN; RAM S. VISWANATH; PAUL R. START; RAJEN S. SIDHU;
RAJASEKARAN SWAMINATHAN**

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

METHODS OF FORMING ULTRA THIN PACKAGE STRUCTURES INCLUDING LOW TEMPERATURE SOLDER AND STRUCTURES FORMED THEREBY

(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on _____ as
United States Application Number _____ and

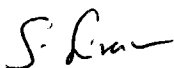
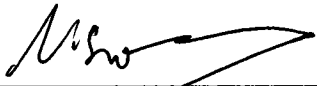


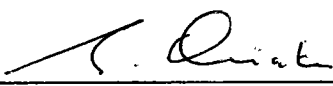
which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

**INTEL CORPORATION
LCA/PAL FORMS**

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

 _____ Sriram Srinivasan	<u>1/2/2013</u> (Today's Date)
 _____ Ram S. Viswanath	<u>1/2/2013</u> (Today's Date)
 _____ Paul R. Start	<u>1-2-13</u> (Today's Date)
 _____ Rajen S. Sidhu	<u>01/03/13</u> (Today's Date)
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